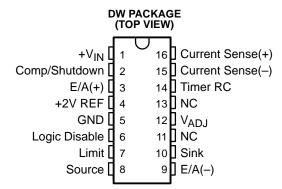
- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of –40°C to 105°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product Change Notification
- Qualification Pedigree<sup>†</sup>
- Precision 1% Reference
- Over-Current Sense Threshold Accurate to 5%
- Programmable Duty-Ratio Over-Current Protection
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- 4.5 V to 36 V Operation
- 100 mA Output Drive, Source or Sink
- Under-Voltage Lockout
- Adjustable Current Limit to Current Sense Ratio
- Separate +V<sub>IN</sub> terminal
- Programmable Driver Current Limit
- Access to VREF and E/A(+)
- Logic-Level Disable Input



NC = No Connect

## description

The UC2832 series of precision linear regulators include all the control functions required in the design of very low dropout linear regulators. Additionally, they feature an innovative duty-ratio current limiting technique which provides peak load capability while limiting the average power dissipation of the external pass transistor during fault conditions. When the load current reaches an accurately programmed threshold, a gated-astable timer is enabled, which switches the regulator's pass device off and on at an externally programmable duty-ratio. During the on-time of the pass element, the output current is limited to a value slightly higher than the trip threshold of the duty-ratio timer. The constant-current-limit is programmable on the UC2832 to allow higher peak current during the on-time of the pass device. With duty-ratio control, high initial load demands and short circuit protection may both be accommodated without extra heat sinking or foldback current limiting. Additionally, if the timer pin is grounded, the duty-ratio timer is disabled, and the IC operates in constant-voltage/constant-current regulating mode.

These IC's include a 2 Volt  $(\pm 1\%)$  reference, error amplifier, UVLO, and a high current driver that has both source and sink outputs, allowing the use of either NPN or PNP external pass transistors. Safe operation is assured by the inclusion of under-voltage lockout (UVLO) and thermal shutdown.

#### ORDERING INFORMATION‡

TA	PACK	AGE§	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
-40°C to 105°C	SOP – DW	Tape and reel	UC2832TDWREP	UC2832TEP		
-40°C to 105°C	SOP - DW	Tube	UC2832TDWEP	UC2832TEP		

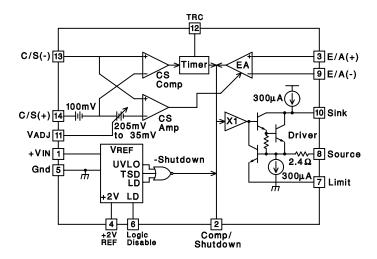
<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



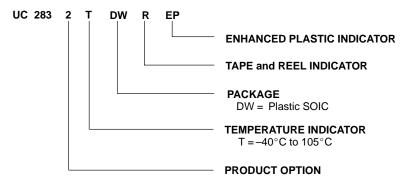
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## block diagram



## **Ordering Information**





## 

## electrical characteristics, $T_A = -40^{\circ}C$ to $105^{\circ}C$ for the UC2832T-EP, $+V_{IN} = 15$ V, Driver sink = $+V_{IN}$ , C/S(+) voltage = $+V_{IN}$ , and $T_A = T_J$ (unless otherwise stated)

PARAMETER	TEST CONDITIONS				TYP	MAX	UNITS
Input Supply	<u>.</u>						
	+V <sub>IN</sub> = 6 V		6.5	10			
Supply current	+V <sub>IN</sub> = 36 V				9.5	15	mA
	Logic Disable = 2 V				3.3	10	
Reference Section							
Output valtage	J 10 mA		T <sub>J</sub> = 25°C	1.98	2	2.02	V
Output voltage	IDRIVER = 10 mA		T <sub>J</sub> = Full range	1.96	2	2.04	
Load regulation voltage	I <sub>OUT</sub> = 0 to 10 mA			-10	-5	10	mV
Line regulation	$+V_{IN} = 4.5 \text{ V to } 36 \text{ V},$	+V <sub>IN</sub> = 4.5 V to 36 V, I <sub>DRIVER</sub> = 10 mA				0.5	mV/V
Under-voltage lockout threshold					3.6	4.5	V
Logic Disable Input							
Threshold voltage				1.3	1.4	1.5	V
Input bias current	Logic Disable = 0 V			-5	-1	0.1	μА
Current Sense Section							
Comparator offset	$T_J = 25^{\circ}C$	95	100	105	mV		
Comparator onset	T <sub>J</sub> = Full range	93	100	107	IIIV		
	V <sub>ADJ</sub> = Open			110	135	170	
Amplifier offset	$V_{ADJ} = 1 V$	180	235	290	mV		
	$V_{ADJ} = 0 V$	250	305	360			
Input bias current	$V_{CM} = +V_{IN}$			65	100	135	μΑ
Input offset current	VCM = +VIN			-10		10	μΑ
Amplifier CMRR	$V_{CM} = 4.1 \text{ V to } + V_{IN} + 0.3$	V			80		dB
Transconductance	$I_{COMP} = \pm 100 \mu A$				65		ms
V <sub>ADJ</sub> input current	V <sub>ADJ</sub> = 0 V			-10	-1		μА



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>‡</sup> Unless otherwise indicated, voltages are reference to ground and currents are positive into and negative out of the specified terminals.

# electrical characteristics, $T_A = -40^{\circ} C$ to $105^{\circ} C$ for the UC2832T-EP, $+V_{IN} = 15$ V, Driver sink = $+V_{IN}$ , C/S(+) voltage = $+V_{IN}$ , and $T_A = T_J$ (unless otherwise stated)

PARAMETER	TEST COI	TEST CONDITIONS				UNITS
Timer						
Inactive leakage current	$C/S(+) = C/S(-) = +V_{IN},$	$C/S(+) = C/S(-) = +V_{IN},$ TRC pin = 2 V				μΑ
Active pull-up current	$C/S(+) = +V_{IN},$ $C/S(-)$ TRC pin = 0 V	$C/S(+) = +V_{IN},$ $C/S(-) = +V_{IN} - 0.4 V,$ TRC pin = 0 V				μΑ
Duty ratio (See Note 1)	ontime/period, $R_T = 2$	200 kΩ, $C_T = 0.27 \mu F$		4.8		%
Period (See Notes 1 and 2)	ontime + offtime, $R_T = 2$	200 kΩ, $C_T = 0.27 \mu F$		36		ms
Upper trip threshold (V <sub>u</sub> )				1.8		V
Lower trip threshold (V <sub>I</sub> )				0.9		V
Trip threshold ratio	V <sub>u</sub> / V <sub>I</sub>			2.0		V/V
Error Amplifier Section	·					
Input offset voltage	V <sub>CM</sub> = V <sub>COMP</sub> = 2 V	V <sub>CM</sub> = V <sub>COMP</sub> = 2 V				mV
Input bias current	V <sub>CM</sub> = V <sub>COMP</sub> = 2 V	V <sub>CM</sub> = V <sub>COMP</sub> = 2 V				μΑ
Input offset current	V <sub>CM</sub> = V <sub>COMP</sub> = 2 V	V <sub>CM</sub> = V <sub>COMP</sub> = 2 V				μΑ
Open loop voltage gain (A <sub>VOL)</sub>	V <sub>COMP</sub> = 1 V to 13 V	V <sub>COMP</sub> = 1 V to 13 V				dB
Common mode rejection ratio (CMRR)	$V_{CM} = 0 V to + V_{IN} - 3 V$	V <sub>CM</sub> = 0 V to +V <sub>IN</sub> - 3 V				dB
PSRR	$V_{CM} = 2 \text{ V}, +V_{IN} = 4.5 \text{ V to}$	V <sub>CM</sub> = 2 V, +V <sub>IN</sub> = 4.5 V to 36 V				dB
Transconductance	$I_{COMP} = \pm 10 \mu A$	I <sub>COMP</sub> = ±10 μA				ms
High-level output voltage (VOH)	I <sub>COMP</sub> = 0, Volts t	ICOMP = 0, Volts below +VIN			1.3	V
Low-level output voltage (VOL)	I <sub>COMP</sub> = 0	ICOMP = 0				V
Output high current (IOH)	V <sub>COMP</sub> = 2 V	V <sub>COMP</sub> = 2 V				μΑ
Outrot law surrent (I	V 0.V	$C/S(-) = +V_{IN}$	100	500	700	μΑ
Output low current (I <sub>OL</sub> )	V <sub>COMP</sub> = 2 V	$C/S(-) = +V_{IN} - 0.4 V$	2	6		mA

NOTES: 1. These parameters are first-order supply-independent, however, both may vary with supply for +V<sub>IN</sub> less than about 4 V. This supply variation will cause a slight change in the timer period and duty cycle, although a high off-time/on-time ratio will be maintained.

2. With recommended RT value of 200 k $\Omega$ , TOFF  $\approx$  RT CT \* In(Vu/VI)  $\pm$  10%.



## electrical characteristics, $T_A = -40^{\circ} C$ to $105^{\circ} C$ for the UC2832T-EP, $+V_{IN} = 15$ V, Driver sink = $+V_{IN}$ , C/S(+) voltage = $+V_{IN}$ , and $T_A = T_J$ (unless otherwise stated)

PARAMETER	TEST CONDITI	MIN	TYP	MAX	UNITS		
Driver Section							
Maximum current	Deliver limit and accurate rise accurate	T <sub>J</sub> = 25°C	200	300	400		
	Driver limit and source pins common	T <sub>J</sub> = Full range	100	300	450	mA	
Limiting voltage	Driver limit to source voltage at currer ISOURCE = $-10$ mA, T <sub>J</sub> = $25$ °C,		0.72		V		
Internal current sense resistance	$T_J = 25^{\circ}C$ , See Note 3	T <sub>J</sub> = 25°C, See Note 3				Ω	
Pull-up current at driver sink		Driver sink = $+V_{IN} - 1 V$	-800	-300	-100		
	Compensation/Shutdown = 0.4 V	+V <sub>IN</sub> = 36 V, Driver sink = 35 V	-1000	-300	<b>-</b> 75	μΑ	
Pull-down current at driver source	Compensation/Shutdown = 0.4 V, Driver source = 1 V	150	300	700	μΑ		
Saturation voltage sink to source	Driver source = 0 V, Driver current		1.5		V		
Maximum source voltage	Driver sink = +V <sub>IN</sub> , Driver current = 1 Volts below +V <sub>IN</sub>		3		٧		
UVLO sink leakage	$+V_{IN} = C/S(+) = C/S(-) = 2.5 \text{ V}, \text{ Driver source} = 0 \text{ V}, T_A = 2$		25		μΑ		
Maximum reverse source voltage	Compensation/Shutdown = 0 V, I <sub>SOL</sub> (+)V <sub>IN</sub> = 3 V		1.6	_	V		
Thermal shutdown			160		°C		

NOTES: 3. The internal current limiting voltage has a temperature dependence of approximately –2.0 mV/°C, or –2800 ppm/°C. The internal 2.4 Ω sense resistor has a temperature dependance of approximately +1500 ppm/°C.

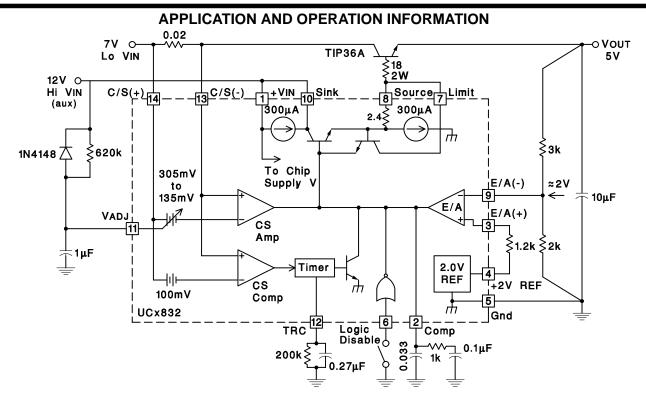


Figure 1. NPN Pass (Medium Power, Low Drop-Out Regulator)



#### APPLICATION AND OPERATION INFORMATION

#### **Estimating Maximum Load Capacitance**

For any power supply, the rate at which the total output capacitance can be charged depends on the maximum output current available and on the nature of the load. For a constant-current current-limited power supply, the output will come up if the load asks for less than the maximum available short-circuit limit current.

To ensure recovery of a duty-ratio current-limited power supply from a short-circuited load condition, there is a maximum total output capacitance which can be charged for a given unit ON time. The design value of ON time can be adjusted by changing the timing capacitor. Nominally,  $T_{ON} = 0.693 \times 10 \text{ k}\Omega \times C_T$ .

Typically, the IC regulates output current to a maximum of  $I_{MAX} = K \times I_{TH}$ , where  $I_{TH}$  is the timer trip-point current, and

$$K = \frac{Current \ Sense \ Amplifier \ Offset \ Voltage}{100 \ mA}$$

and is variable from 1.35 to 3.05 with V<sub>ADJ</sub>.

For a worst-case constant-current load of value just less than I<sub>TH</sub>, C<sub>MAX</sub> can be estimated from:

$$C_{MAX} = \left(\frac{K-1}{TH}\right) \times \left(\frac{T_{ON}}{V_{OUT}}\right)$$

where V<sub>OUT</sub> is the nominal regulator output voltage.

For a resistive load of value R<sub>L</sub>, the value of C<sub>MAX</sub> can be estimated from:

$$C_{MAX} = \frac{T_{ON}}{R_{L}} \times \frac{1}{In \left[ \left( 1 - \frac{V_{OUT}}{K \times I_{TH} \times R_{L}} \right)^{-1} \right]}$$

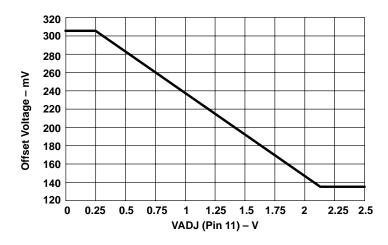


Figure 2. Current Sense Amplifier Offset Voltage vs V<sub>ADJ</sub>



### **APPLICATION AND OPERATION INFORMATION**

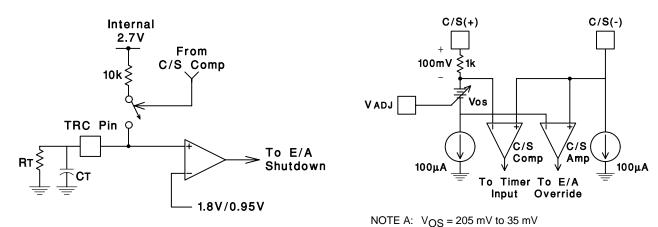


Figure 3. Timer Function

**Figure 4. Current Sense Input Configuration** 

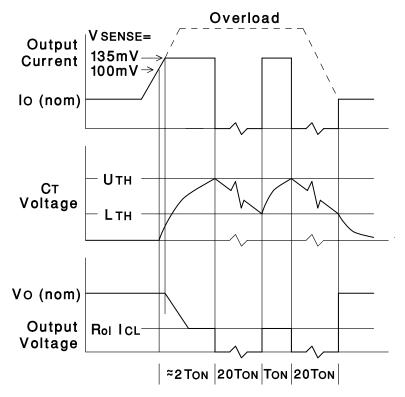


Figure 5. Load Current, Timing Capacitor Voltage, and Output Voltage of the Regulator Under Fault Conditions

### APPLICATION AND OPERATION INFORMATION

## **UCx832 Error Amplifier**

#### AVOL vs Frequency and CC 120 100 1500pF 80 AVOL - (dB) 60 40 20 0 -20 1E+00 1E+01 1E+02 1E+03 1E+04 1E+05 1E+06 Frequency - (Hz)

Figure 6. UCx832 Error Amplifier

#### **UCx832 Error Amplifier**

Transconductance and Phase vs Frequency

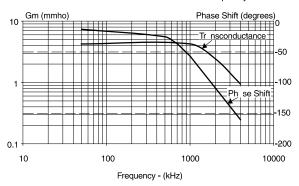


Figure 8. UCx832 Error Amplifier

### **UCx832 Current Sense Amplifier**

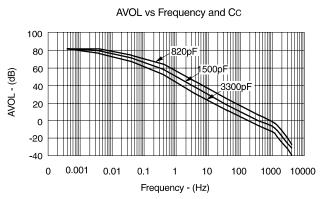


Figure 7. UCx832 Current Sense Amplifier

### **UCx832 Current Sense Amplifier**

Transconductance and Phase vs Frequency

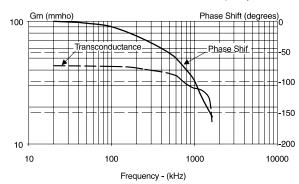


Figure 9. UCx832 Current Sense Amplifier



## PACKAGE OPTION ADDENDUM

17-Dec-2015

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
UC2832TDWEP	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 105	UC2832TEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

17-Dec-2015

#### OTHER QUALIFIED VERSIONS OF UC2832-EP:

www.ti.com

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

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